

# 30V N-Channel Enhancement Mode Power MOSFET

# **Description**

WMQ37N03T1 uses advanced power trench technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

#### **Features**

•  $V_{DS} = 30 \text{ V}, I_D = 37 \text{ A}$ 

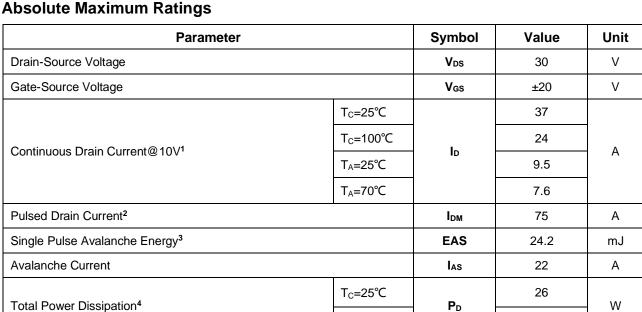
 $R_{DS(on)} < 12m\Omega$  @  $V_{GS} = 10 \text{ V}$ 

 $R_{DS(on)} < 16.5 \text{m}\Omega$  @  $V_{GS} = 4.5 \text{V}$ 

- Green Device Available
- Low Gate Charge
- Advanced High Cell Density Trench Technology
- 100% EAS Guaranteed



- **Power Management Switches**
- DC/DC Converter

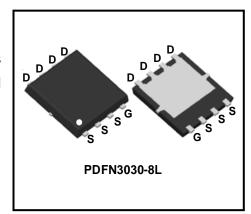


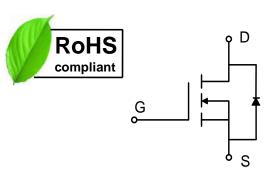
#### **Thermal Characteristics**

Operating Junction and Storage Temperature Range

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient <sup>1</sup>	R <sub>0JA</sub>	75	°C/W
Thermal Resistance from Junction-to-Case <sup>1</sup>	Rелс	4.8	°C/W

T<sub>A</sub>=25°C





1.67

-55 to+150

TJ, TSTG

°C



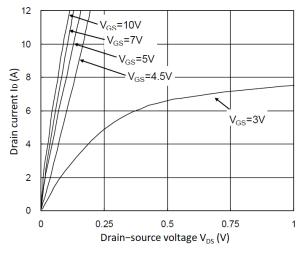
## Electrical Characteristics T<sub>c</sub> = 25°C, unless otherwise noted

Parameter		Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static Characteristics							
Drain-Source Breakdown V	oltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0V, I_D = 250\mu A$	30	-	-	V
Gate-Body Leakage current		Igss	$V_{DS} = 0V, V_{GS} = \pm 20V$	-	-	±100	nA
Zero Gate Voltage Drain Current	T <sub>J</sub> =25°C	I <sub>DSS</sub>	V <sub>DS</sub> = 24V, V <sub>GS</sub> = 0V	-	-	1	μΑ
	T <sub>J</sub> =55°C			-	-	5	
Gate-Threshold Voltage		V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_D = 250\mu A$	1.0	1.7	2.5	V
	•	_	V <sub>GS</sub> = 10V, I <sub>D</sub> = 15A	-	9	12	mΩ
Drain-Source On-Resistance	ce²	R <sub>DS(on)</sub>	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 10A	-	12	16.5	
Forward Transconductance		<b>g</b> fs	$V_{DS} = 5V, I_{D} = 15A$	-	24	-	S
Dynamic Characteristic	cs				l		
Input Capacitance		Ciss		-	830	-	
Output Capacitance  Reverse Transfer Capacitance		Coss	V <sub>DS</sub> = 15V, V <sub>GS</sub> =0V, f =1MHz	-	126	-	pF
		C <sub>rss</sub>		-	85	-	
Switching Characterist	ics	1					
Gate Resistance		Rg	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$	-	2.1	-	Ω
Total Gate Charge		Qg		-	9.8	-	
Gate-Source Charge Gate-Drain Charge		Q <sub>gs</sub>	$V_{GS} = 4.5V$ , $V_{DS} = 15V$ , $I_{D} = 12A$	-	2.2	-	nC
		$Q_{gd}$		-	5.5	-	
$ \begin{array}{cccc} \text{Turn-On Delay Time} & & & & & \\ \text{Rise Time} & & & & & \\ \text{Turn-Off Delay Time} & & & & \\ \text{Fall Time} & & & & \\ \end{array} \begin{array}{c} \textbf{t}_{d(\text{off})} \\ \textbf{t}_{f} \end{array} $			-	6.4	-		
		t <sub>r</sub>	$V_{GS} = 10V, V_{DD} = 15V,$	-	39	-	nS
		t <sub>d(off)</sub>	$R_G = 1.5\Omega, I_D = 20A$	-	21	-	
		t <sub>f</sub>		-	4.7	-	
Drain-Source Body Dio	de Charac	teristics	1	1	ı		1
Diode Forward Voltage <sup>2</sup>		V <sub>SD</sub>	I <sub>S</sub> = 1A, V <sub>GS</sub> = 0V	-	-	1	V
Continuous Source Current <sup>1,5</sup>		Is	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current	-	-	37	Α

#### Note:

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300 \text{us}$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{DD}$ =25V,  $V_{GS}$ =10V, L=0.1mH,  $I_{AS}$ =22A
- 4.The power dissipation is limited by 150°C junction temperature
- 5. The data is theoretically the same as  $I_{D}$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.





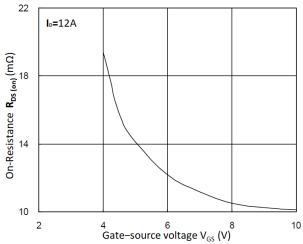
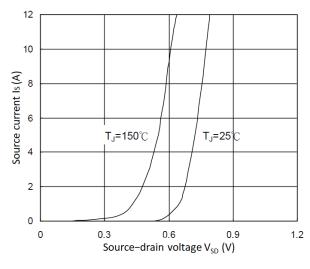


Figure 1. Output Characteristics

Figure 2. R<sub>DS</sub>(on) vs. V<sub>GS</sub>



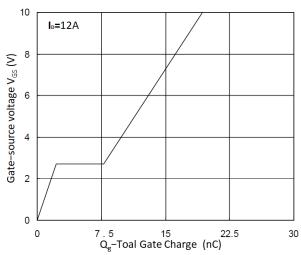
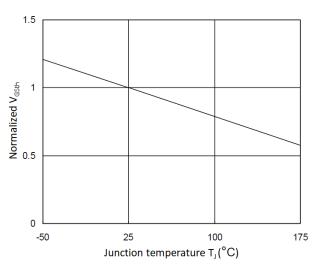


Figure 3. Forward Characteristics of Reverse

Figure 4. Gate Charge Characteristics



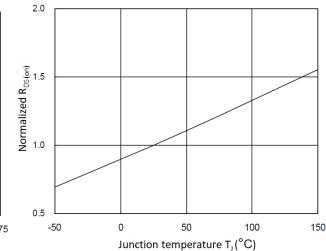


Figure 5. Normalized V<sub>GSth</sub> vs. T<sub>J</sub>

Figure 6. Normalized RDS(on) vs. TJ



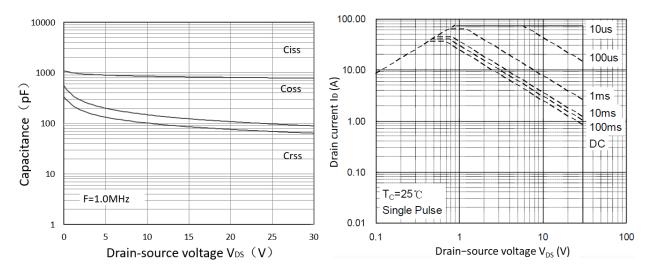


Figure 7. Capacitance Characteristics

Figure 8. Safe Operating Area

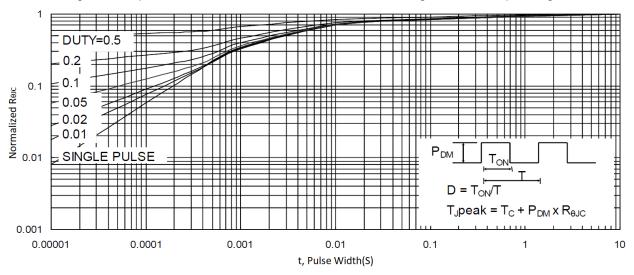


Figure 9. Normalized Maximum Transient Thermal Impedance

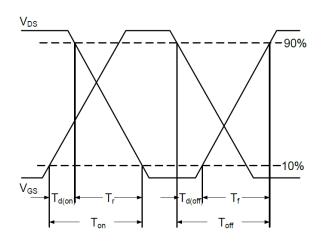


Figure 10. Switching Time Waveform

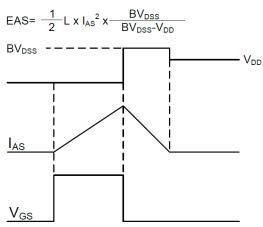
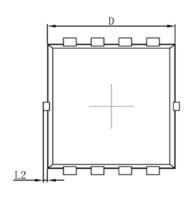


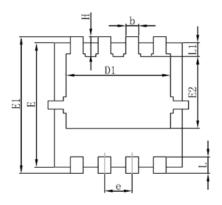
Figure 11. Unclamped Inductive Switching

Waveform



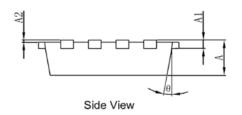
## **Mechanical Dimensions for PDFN3030-8L**





Top View

Bottom View



# **COMMON DIMENSIONS**

	MM			
SYMBOL	MIN	MAX		
А	0.70	0.90		
A1	0.150REF			
A2	0	0.05		
D	2.90	3.25		
D1	2.25	2.65		
E	2.90	3.20		
E1	3.10	3.45		
E2	1.54	1.94		
b	0.20	0.40		
е	0.60	0.70		
L	0.30	0.50		
L1	0.22	0.45		
L2	0	0.13		
Н	0.20	0.65		
θ	0°	14°		



## **Ordering Information**

Part	Package	Marking	Packing method
WMQ37N03T1	PDFN3030-8L	Q37N03	Tape and Reel

## **Marking Information**



Q37N03 = Device code WWXX XXX= Date code

# **Contact Information**

No.1001, Shiwan(7) Road, Pudong District, Shanghai, P.R.China.201207 Tel: 86-21-50310888 Fax: 86-21-50757680 Email: market@way-on.com

WAYON website: http://www.way-on.com

For additional information, please contact your local Sales Representative.

**Ⅲ (Partial Partial Partial** 

#### **Disclaimer**

WAYON reserves the right to make changes without further notice to any Products herein to improve reliability, function, or design. The Products are not designed for use in hostile environments, including, without limitation, aircraft, nuclear power generation, medical appliances, and devices or systems in which malfunction of any Product can reasonably be expected to result in a personal injury. The information given in this document shall in no event be regarded as a guarantee of conditions or characteristics. WAYON does not assume any liability for infringement of patents, copyrights, or other intellectual property rights of third parties by or arising from the use of Products or technical information described in this document.